

**AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions and listings of claims in the Application.

1. (Currently Amended) A viscosity reducible radiation curable composition comprising at least one radiation curable component, a thixotropic agent, a flow aid selected from the group consisting of polyacrylates, polyalkyleneoxide modified polydimethylsiloxane, and ethyl acrylate-2-ethylhexyl acrylate copolymer, and a filler, wherein the composition has the properties:

- i) a yield stress value of  $< 1100$  Pa,
- ii) a viscosity (at a shear rate of  $1 \text{ sec}^{-1}$ ) between 1 and 1500 Pa.sec, and
- iii) a filler settling speed less than 0.3 mm/day.

2. (Currently Amended) A viscosity reducible radiation curable composition comprising at least one radiation curable component, a thixotropic agent, a flow aid selected from the group consisting of polyacrylates, polyalkyleneoxide modified polydimethylsiloxane, and ethyl acrylate-2-ethylhexyl acrylate copolymer, and a filler, wherein the composition has the properties:

- i) a yield stress value of  $< 1100$  Pa,
- ii) a viscosity (at a shear rate of  $10 \text{ sec}^{-1}$ ) between 1 and 200 Pa.sec, and
- iii) a filler settling speed less than 0.3 mm/day.

3. (Previously Presented) The radiation curable composition according to claim 1, wherein the yield stress value is  $< 500$  Pa.

4. (Previously Presented) The radiation curable composition according to claim 1, wherein the composition comprises at least one photoinitiator.

5. (Previously Presented) The radiation curable composition according to claim 1, wherein the composition has a thixotropic index of at least 3.

6-12. (Cancelled)

13. (Previously Presented) The radiation curable composition according to claim 1, wherein the composition comprises cationically curable components, and radically curable components.

14. (Currently Amended) The radiation curable composition according to claim ~~9~~1, wherein the composition, relative to the total weight of the radiation curable composition, comprises between 30 and 90 wt% of cationically curable components.

15. (Currently Amended) The radiation curable composition according to claim 1, wherein the composition, relative to the total weight of the radiation curable composition, comprises between 5 and 50 wt% of radically polymerizable components.

16. (Currently Amended) A viscosity reducible radiation curable composition comprising relative to the total weight of the radiation curable composition:

5-70 wt% of a difunctional epoxy compound;

0.1-15 wt% of an acrylate having a functionality of larger than 2;

0.1-10 wt% of a thixotropic agent ;

0.01-5 wt% of a flow aid selected from the group consisting of polyacrylates, polyalkyleneoxide modified polydimethylsiloxane, and ethyl acrylate-2-ethylhexyl acrylate copolymer;

10-90 wt% of a filler ; and

at least one photoinitiator .

17. (Original) The composition according to claim 16, wherein the composition has the properties:

- i) a yield stress value of  $< 1000$  Pa,
- ii) a viscosity (at a shear rate of  $1 \text{ sec}^{-1}$ ) between 0 and 1500 Pa.sec, and
- iii) a filler settling speed less than 0.3 mm/day.

18. (Withdrawn) A method for forming a three-dimensional object comprising the steps of:

- a) coating a layer of a viscosity reduced composition as define in claim 1 on a surface;
- b) allowing said layer to become a viscosity reducible composition layer having a viscosity greater than said viscosity reduced layer;
- c) exposing said viscosity reducible layer to radiation imagewise by radiation means in order to photoform said layer imagewise;
- d) repeating steps a) through c) until the three dimensional object is being formed.

19-20. (Cancelled)

21. (Previously Presented) The composition according to claim 16, wherein the difunctional epoxy compound is selected from the group consisting bisphenol A diglycidyl ether, bisphenol F diglycidyl ether, hydrogenated bisphenol A diglycidyl ether, hydrogenated bisphenol F diglycidyl ether, 3,4-epoxycyclohexylmethyl-3',4'-epoxycyclohexane carboxylate, bis(3,4-epoxycyclohexylmethyl)adipate, 1,4-butanediol diglycidyl ether, 1,6-hexanediol diglycidyl ether, polyethylene glycol diglycidyl ether, and polypropylene glycol diglycidyl ether.

22. (Previously Presented) The composition according to claim 16, wherein the acrylate having a functionality of larger than 2 is selected from the group consisting of

trimethylolpropane tri(meth)acrylate, ethylene oxide-modified trimethylolpropane tri(meth)acrylate, dipentaerythritol hexa(meth)acrylate, dipentaerythritol penta(meth)acrylate, and ditrimethylolpropane tetra(meth)acrylate.

23. (Previously Presented) The composition according to claim 16, wherein the thixotropic agent is selected from the group consisting of polyvinylpyrrolidone, titanate coupling agents, aluminum distearate, aluminium tristearate, copolymers with acidic groups, fumed silica, organic derivatives of castor oil and polyoxyethylene-polyoxypropylene block copolymers.

24. (Currently Amended) The composition according to claim 16, wherein said composition further comprises one or more ~~selected from~~ of the following components: ~~photosensitizer consisting of amine compounds; photosensitizers consisting of~~ thioxanethone, derivatives of thioxanethone, anthraquinone, derivatives of anthraquinone, anthracene, derivatives of anthracene, perylene, derivatives of perylene, benzophenone, benzoin isopropyl ether; photosensitizers; reactive diluents; resins such as epoxy resin, polyamide, polyamideimide, polyurethane, polybutadiene, polychloroprene, polyether, polyester, styrene/butadiene styrene block copolymer, petroleum resin, xylene resin, ketone resin, cellulose resin, fluorine containing oligomer, and silicon containing oligomer; polymerization inhibitors; polymerization initiation assistants; levelling agents; wettability improvers; surfactants; plasticizers; UV absorbers; silane coupling agents; resin particles; pigments; and dyes.

- A. photosensitizers;
- B. reactive diluents;
- C. resins;
- D. polymerization inhibitors;
- E. polymerization initiation assistants;
- F. leveling agents;

- G. wettability improvers;
- H. surfactants;
- I. plasticizers;
- J. UV absorbers;
- K. silane coupling agents;
- L. resin particles;
- M. pigments; and
- N. dyes.

25. (New) The composition according to claim 24 wherein element A is selected from the group consisting of amine compounds, tioxanethone and derivatives thereof, anthraquinone and derivatives thereof, anthracene and derivatives thereof, perylene and derivatives thereof, benzophenone, and benzoin isopropyl ether.

26. (New) The composition according to claim 24, wherein element C is selected from the group consisting of epoxy resin, polyamide, polyamideimide, polyurethane, polybutadiene, polychloroprene, polyether, polyester, styrene/butadiene styrene block copolymer, petroleum resin, xylene resin, ketone resin, cellulose resin, fluorine containing oligomer, and silicon containing oligomers.